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Materials Declaration Form

IPC **Form Type ***	**1752** Distribute	**Version**	**2**
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D **** : Required Field***

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2015-07-17**
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	**Laurent TOSI**	**Representative Title**	**MMS MD CHAMPION**
Representative Phone *	33 442 685 795	**Representative Email ***	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed
by Laurent Tosi
Date: 2015.07.17
19:11:55 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
M24C32-WMN6TP	PGO7*24321KA	A	3068	2015-07-17
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	80.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
SON	STD JEDEC	8	L bend	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th June 2014

Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**PGO7*24321KA**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	0.650	mg	supplier	die	Silicon (Si)	7440-21-3		0.624	mg	960000	7800
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3077	25
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.002	mg	3077	25
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.002	mg	3077	25
die (s)				supplier	passivation	Indium Tin oxide (In203:SnO2)	50926-11-9		0.020	mg	30769	250
Lead-frame	Other inorganic materials	24.984	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.347	mg	974500	304339
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.586	mg	23460	7327
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.030	mg	1200	375
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.021	mg	840	262
Lead-frame Coating	Other inorganic materials	0.124	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	916800	1425
Lead-frame Coating				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	58700	91
Lead-frame Coating				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	24500	38
Die Attach	Other inorganic materials	1.027	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.925	mg	900000	11557
Die Attach				supplier	glue or soft solder	acrylate	na		0.062	mg	60000	770
Die Attach				supplier	glue or soft solder	Methacrylate	na		0.039	mg	38000	488
Die Attach				supplier	glue or soft solder	acrylate	na		0.002	mg	2000	26
Wires	Other inorganic materials	0.062	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.062	mg	1000000	776
Encapsulation	Other inorganic materials	53.151	mg	supplier	Moulding Compound	Epoxy Resin	na		3.938	mg	74093	49226
Encapsulation				supplier	Moulding Compound	Phenol Resin	na		2.625	mg	49395	32818
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		46.115	mg	867621	576434
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		0.263	mg	4940	3282
Encapsulation				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.210	mg	3952	2625
Finishing	Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	916800	14
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	1
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0